



# 2007 IEEE



## Compound Semiconductor IC Symposium

INTEGRATED CIRCUITS IN GaAs, InP, SiGe, GaN and OTHER COMPOUND SEMICONDUCTORS



October 14 – 17, 2007  
Hilton Portland & Executive Tower  
Portland, Oregon, USA



Sponsored by the IEEE Electron Devices Society  
Technically co-sponsored by the Solid State Circuits Society  
and the Microwave Theory & Techniques Society



### FINAL CALL FOR PAPERS

#### 2007 CSIC Symposium

Over the last 29 years, the Compound Semiconductor IC Symposium (CSICS) has become the preeminent international forum on developments in integrated circuits using compound semiconductors such as GaAs, InP, GaN, SiGe and other materials. Coverage embraces all aspects of the technology, from materials issues and device fabrication, through IC design and testing, high volume manufacturing, and system applications. The CSIC Symposium provides the ideal forum to present your latest results in high-speed digital, analog, microwave/millimeter wave, mixed mode, and optoelectronic integrated circuits. First-time papers concerned with the utilization and application of InP, GaAs, SiGe, GaN and other compound semiconductors in military and commercial products are invited. Specific technical areas of interest include:

- Innovative RFIC Device & Circuit Concepts
- Millimeter-wave/High-Speed CMOS IC
- Circuit Design & Fabrication
- Manufacturing Technology & Cost Issues
- CAD/CAM/CAT Tools & Techniques
- IC Testing & Methodology
- Packaging Technology
- Reliability
- Advanced Device Applications
- System Applications (e.g., wireless, vehicular, RADAR, military)
- Optoelectronic and OEIC applications

#### Symposium Highlights

High quality technical papers will be selected from worldwide submissions for presentation and publication in the Symposium Digest. Invited papers and panel sessions on hot topics for the Compound Semiconductor IC community will complete the program. Extended versions of selected papers will be published in a special issue of the *IEEE Journal of Solid State Circuits*.

#### Compound Semiconductor Primer Course

The Symposium will again offer the popular primer course, "Basics of GaAs, InP and SiGe RFICs," which is an introductory-level class intended for those wishing to obtain a broad overview of RFIC technology. The Sunday evening course will cover materials and processes, device operation, and both analog/microwave and digital ICs. It will provide the specific background needed to understand and appreciate the papers presented in the Symposium Technical Program.

#### Short Course

Two short courses will be held on Sunday, October 14th. The courses are entitled "Compound Semiconductor Devices and Integrated Circuits for Millimeter Wave Imaging" and "Compound Semiconductor Power Amplifiers." Organizer: Marko Sokolich, HRL Laboratories, LLC, e-mail: msokolich@hrl.com, phone: +1-310-317-5148.

#### CSICS Theme Party

Once again, we have a special evening ready for all. We will get a flavor of some of the local culture with an evening at McMenamins Pubs and Breweries Crystal Ballroom. As part of the entertainment, there will be both wine and beer tasting of Oregon produced beverages. We hope to see y'all in Portland!

### Deadline for Electronic Receipt of Abstracts is Close of Business, May 7, 2007

Authors must submit an Abstract (not more than 4 pages including figures and other supporting material) of results not previously published or not already accepted by another conference. Papers will be selected on the basis of the abstract.

**The abstract must concisely and clearly state:**

- a) **The purpose of the work**
- b) **What specific new results have been obtained**
- c) **How it advances the state-of-art or the industry**
- d) **References to prior state-of-art**
- e) **Sub-committee preference:**
  - **Digital OEIC,**
  - **Analog RF/Microwave,**
  - **Technology/Manufacturing**
  - **CMOS Technology and ICs**

The abstract must include: the title, name(s) of the authors(s), organization(s) represented, correspondence authors' postal and electronic addresses, and telephone and FAX numbers. Please indicate your preference for subcommittee review. The program committee will honor the authors' preference where possible, but reserves the right to place the paper in other review categories.

**Company and governmental clearances must be obtained prior to submission of the abstract.**

The accepted abstracts may be used for publicity purposes. Portions of these abstracts may be quoted in magazine articles publicizing the Symposium. **Please note on the abstract if this is not acceptable.**

Authors must submit the Abstract electronically using the [www.csics.org](http://www.csics.org) web page. Please note that the **only** accepted file format is **PDF**. Authors will be informed regarding the results of their submissions by June 16, 2007. Authors of accepted papers will be required to submit an **MS-Word version** of a 4-page camera-ready extended abstract to IEEE by July 13, 2007 for publication in the Symposium Technical Digest.

Further questions on abstract submission may be addressed to the Symposium Technical Program Chair:

William Peatman  
TEL: 1-908-668-5000 ext. 5842  
Email: [wpeatman@anadigics.com](mailto:wpeatman@anadigics.com)

All Symposium information, including abstract submission instructions and a link to our abstract submission address is available on our website at:

<http://www.csics.org/>

## 2007 Compound Semiconductor IC Symposium Exhibition

As in past years, the Symposium will sponsor an exhibition of products from various vendors of materials, IC products, processing equipment, test equipment, CAD tools, and foundry services specifically addressing the Compound Semiconductor industry. Numerous vendors will be on-hand to discuss their products and to answer questions. Inquiries concerning the exhibits should be

addressed to: Sue Kingston, 1514 First Street, Manhattan Beach, CA 90266.  
Ph: +1-310-937-1006  
Fax: +1-732-465-6447  
Email: s.kingston@ieee.org

The following members of the Technical Program Committee are available for guidance or for answering questions regarding abstract preparation:

### NORTH AMERICA

Mohammad Madihian  
NEC Laboratories America, Inc.  
Ph: +1-609-951-2916  
Fax: +1-609-951-2499  
Email: madihian@ieee.org

William Peatman  
ANADIGICS, Inc.  
Ph: +1-908-668-5000 ext. 5842  
Fax: +1-908 668-5068  
Email: wpeatman@anadigics.com

### ASIA/PACIFIC

Toshihide Kikkawa  
Fujitsu Laboratories Ltd. (Japan)  
Ph: +81-46-250-8243  
Fax: +81-46-250-4337  
Email: kikkawa.toshi@jp.fujitsu.com

Chul Soon Park  
School of Engineering ICU (Korea)  
Ph: +82-42-866-6125  
Fax: +82-42-866-6110  
E-mail : parkcs@icu.ac.kr

Huei Wang  
National Taiwan University (Taiwan)  
Ph: +886-2-2363-5251 x317  
Fax: +886-2-2368-3824  
Email: hueiwang@ew.ee.ntu.edu.tw

### EUROPE

Marc Rocchi  
OMMIC (France)  
Ph: +33-01-4510-6896  
Fax: +33-01-4510-6953  
Email: m.rocchi@ommic.com

Jan-Erik Mueller  
Infineon Technologies (Germany)  
Ph: +49-89-234-53052  
Fax: +49-89-234-40822  
Email: jan-erik.mueller@infineon.com

Freek van Straten  
NXP Semiconductors (The Netherlands)  
Ph: +31-24-353-5673  
Fax: +31-24-353-5186  
Email: freek.van.straten@nxp.com

## Executive Committee

### **Symposium Chair**

Mohammad Madihian  
NEC Laboratories America, Inc.  
Ph: +1-609-951-2916  
Email: madihian@ieee.org

### **Technical Program Chair**

William Peatman  
ANADIGICS, Inc.  
Ph: +1-908-668-5000 Ext 5842  
Email: wpeatman@anadigics.com

### **Technical Program Vice-Chair**

**Short Course Moderator**  
Marko Sokolich  
HRL Laboratories  
Ph: +1-310-317-5148  
Email: msokolich@hrl.com

### **Local Arrangements Chair**

Dave Halchin  
RF Micro Devices, Inc.  
Ph: +1-336-931-8123  
Email: dhalchin@rfdm.com

### **Treasurer**

Walter Wohlmuth  
RF Micro Devices, Inc.  
Ph: +1-336-678-5808  
Email: wwohlmuth@rfdm.com

### **Publicity Chair**

Dan Scherrer  
Northrop Grumman  
Ph: +1-310-812-5892  
Email: dan.scherrer@ngc.com

### **Publications Chair**

Sorin Voinigescu  
University of Toronto  
Ph: +1-416-946-8664  
Email: sorinv@eecg.toronto.edu

### **Symposium Secretary**

Francois Colomb  
Raytheon RF Components  
Ph: +1-978-684-5435  
Email: fcolomb@raytheon.com

### **Website Administrator**

David Osika  
ANADIGICS, Inc.  
Ph: +1-908-668-5000 Ext 5343  
Email: dosika@anadigics.com

### **Electronic Program Management**

Mohammad Madihian  
NEC Laboratories America, Inc.  
Ph: +1-609-951-2916  
Email: madihian@ieee.org

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If you did not receive this Call for Papers in the mail or by email and would like to be added to our mailing list, please send your name, address, and/or email address to: Dan Scherrer, Northrop Grumman, M5/2486C, One Space Park, Redondo Beach, CA 90278 Ph: +1-310-812-5892, Fax: +1-310-812-5878, Email: dan.scherrer@ngc.com

Institute of Electrical and Electronic Engineers  
445 Hoes Lane  
Piscataway, NJ 08855-1331

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